

卷绕镀铜工艺对复合集流体电学性能影响研究

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摘 要: 为改善锂离子电池用镀铜复合集流体的电学性能, 通过控制卷绕磁控溅射走带速度、阴极功率、工艺压强、线性离子源前处理参数、NiCr 打底层厚度等工艺条件, 在有机基材表面沉积铜膜, 通过四探针方阻测量仪测定镀铜层方阻值, 得到了不同工艺参数对镀铜层方阻的影响规律。结果表明: 随走带速度增加, 方阻值呈二次方增大; 随阴极功率增加, 方阻值呈幂次方降低; 工艺压强 0.13~0.45Pa 范围内, 方阻值在 0.2Pa 时达到最低; 离子源电流 0~0.7A 范围内, 方阻值随离子源电流增大线性降低; NiCr 打底层能够改善镀铜层的方阻, 6.7nm 厚的 NiCr 打底层样品较无打底层样品方阻值降低 23.2%。

关 键 词: 复合集流体; 卷绕镀膜; 磁控溅射; 镀铜; 方块电阻

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Study of the Influence of Process Parameters of Copper Coating Fabricated by Roll to Roll Machine on Electronic Property of Composite Current Collector

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Abstract: By controlling winding speed, cathode power, process pressure, linear ion source current, thickness of NiCr seed layer, roll to roll magnetron sputtering machine was used to deposit nano-copper film on the surface of organic film substrate, in order to improve electronic property of copper current collector. The sheet resistance of copper coating was characterized by four-probe method, and the influence of different process parameters on the sheet resistance of copper coating were obtained. The results show that with the increase of running speed of substrate, the sheet resistance increases quadratically, and with the increase of cathode power, the sheet resistance decreases in power. In the process pressure range of 0.13~0.45Pa, the sheet resistance reaches the minimum at 0.2Pa. With the ion source current increasing in the range of 0~0.7A, the sheet resistance decreases linearly. NiCr seed layer can improve the sheet resistance of copper layer, and the sheet resistance of copper coating with 6.7nm NiCr seed layer is 23.2% lower than that of copper coating without seed layer.

Key words: composite current collector; roll to roll; magnetron sputtering; copper coating; sheet resistance

动力型锂离子电池对减重、降本、安全的需求越来越高。集流体是锂离子电池的重要组成部分,其功用主要是将电池活性物质产生的电流汇集起来以便形成较大的电流对外输出。传统锂离子电池负极采用 4~8 μm 铜箔作为集流体,成本约占锂离子电池的 5%~10%,质量约占锂离子电池的 10%~15%。最新研究表明,通过在厚度不高于 4.5 μm 的 BOPP 或 PET 上沉积 1 μm 左右的铜薄膜,替代传统铜箔,可以实现减重、降本需求,同时起到类似保险丝的作用,在电池内短路时,聚

合物层及时熔断,阻断短路点以防止热扩散,使锂离子电池安全性及循环寿命显著改善^[1-2],因此镀铜复合集流体是较有潜力的铜箔替代方案之一。在超薄柔性基底上一次沉积单面 1 μm 厚的铜较难实现,行业内的普遍做法是采用磁控溅射法制备一层相对较薄的铜打底层(厚度 $\leq 100\text{nm}$,方块电阻 $R_{\square} \leq 1.5\Omega$),随后通过电镀或蒸镀形式增厚至 1 μm ,该方法操作简单、对环境污染低、能实现低温沉积,且薄膜结晶性好、附着力佳^[3-8]。针对复合集流体, $R_{\square}$ 常用来作为衡量能否满足后

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